vireless oscilloscope

Team

- Byron Aguilar
 - AFE Design
 - Team Leader
- Boning Dong
 - FPGA Design
 - Subsystem Interface Design
- Cesar Gonzalez
 - AFE Design
 - Power Management



Wireless Oscilloscope

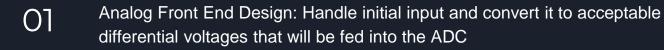
- Appearance of a pen,
 - Easy use with one hand
- Measure arbitrary voltage waveforms
 - Up to 50Vpp
 - Up to 20MHz Bandwidth
- Data Transmitted via WiFi to PC
- Software will provide functionalities of a regular bench-top oscilloscope

Project objective

- Provide engineering hobbyists and students with an alternative tool for their study.
- Design should be
 - Convenient
 - Functional
 - Elegant
 - Affordable



Design Breakdown



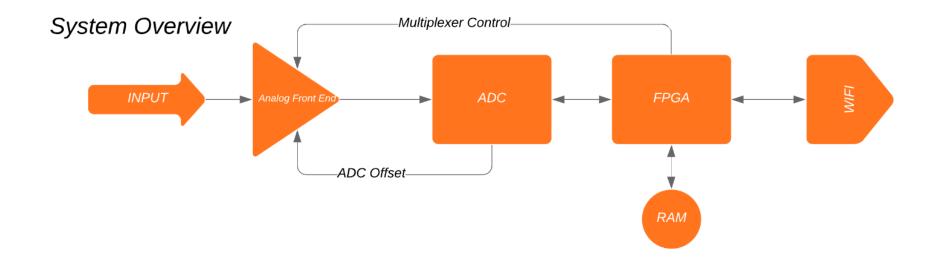
O2 ADC/FPGA/Memory: ADC samples differential signal and transmits data to FPGA. Data is stored and then sent to Wi-Fi module



Software Programming: Receives data and reconstructs the signal. Displays signal

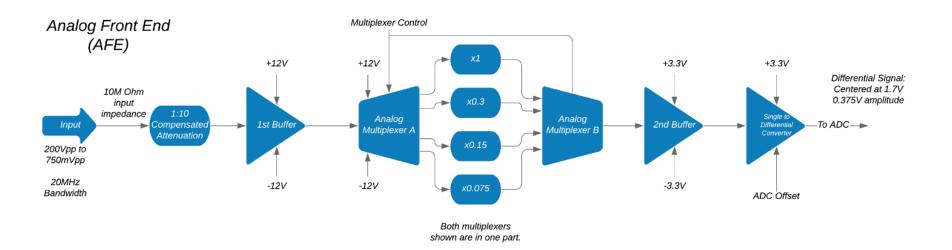


Block Diagram



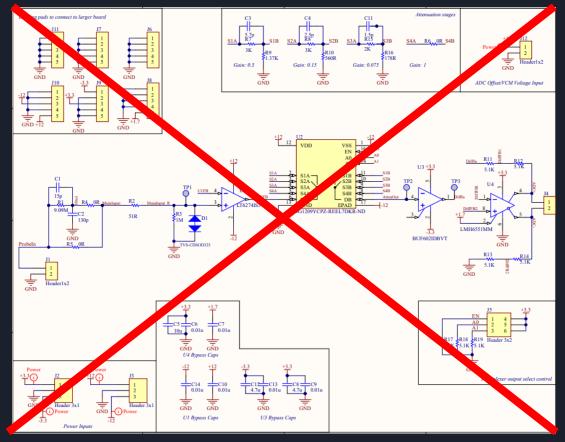
AFE Design Requirements

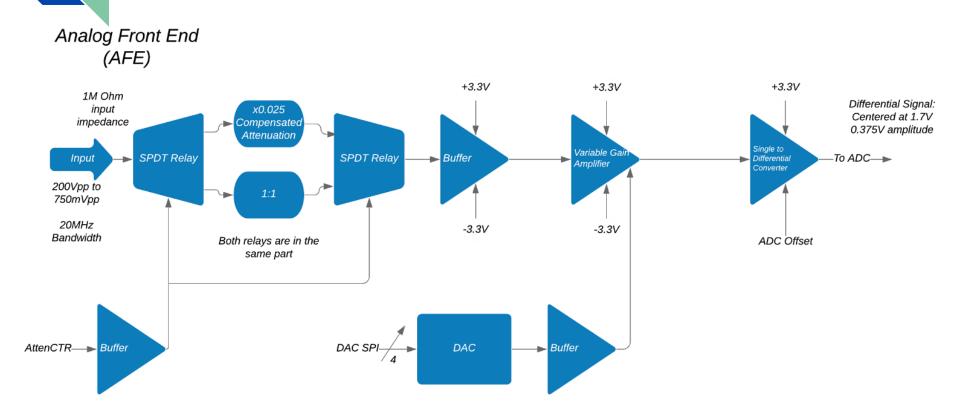
- Input can be almost anything
 - Protection must be included against too high voltages
- Ideal AFE should not distort or modify the general form of the original signal
- AFE should be able to scale an input to the best possible voltage range for the ADC

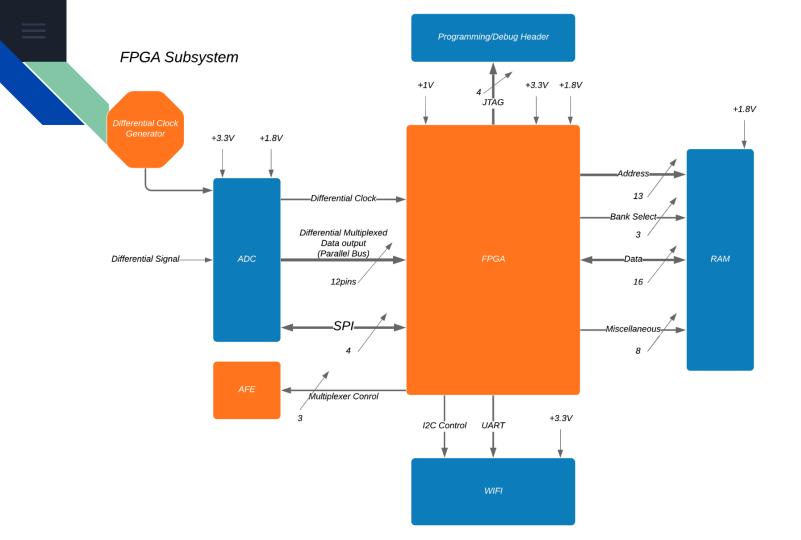




AFE Schematic



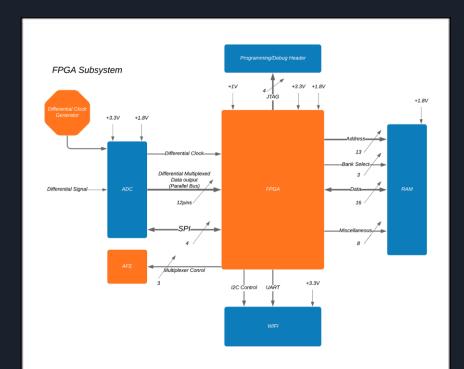






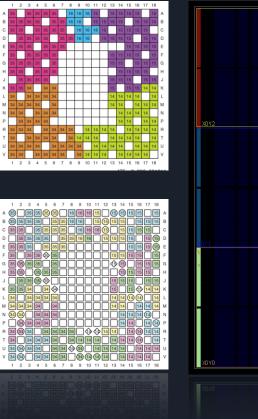
FPGA and Subsystem Interfaces

- Understand FPGA interface
 - FPGA Architecture
 - IO Standards
 - Resources Evaluation
- Under all subsystem interface
 - DDR2 Memory
 - ADC
 - JTAG
 - WIFI (ongoing)
 - MCU (ongoing)



1. FPGA Interface

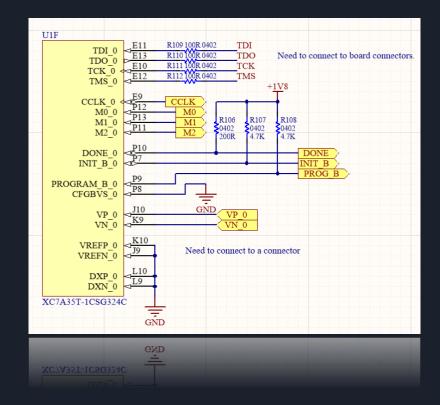
- a. FPGA Architecture
- IOs within the same bank are powered by the same power source.
- Some interface such as memory interface cannot cross banks.
- a. IO Standards
- LVCMOS: Low Voltage CMOS
- LVDS: Low Voltage Differential Signals
- SSTL: Stub Series Terminated Logic
- a. FPGA Resources Evaluation
- Implemented a memory controller to check the resources usage.





2. Subsystem Interface

- a. DDR2 Memory
- SSTL_18 IO Standard
- Controlled using Vivado MIG IP Core.
- [PCB] Requires impedance & length matching
- a. ADC
- Using LVDS_18 IO Standard
- SSTL: Stub Series Terminated Logic
- [PCB] Requires differential pairs.
- a. JTAG
- Pin definition has been given out.
- May need serial resistors for voltage conversion.



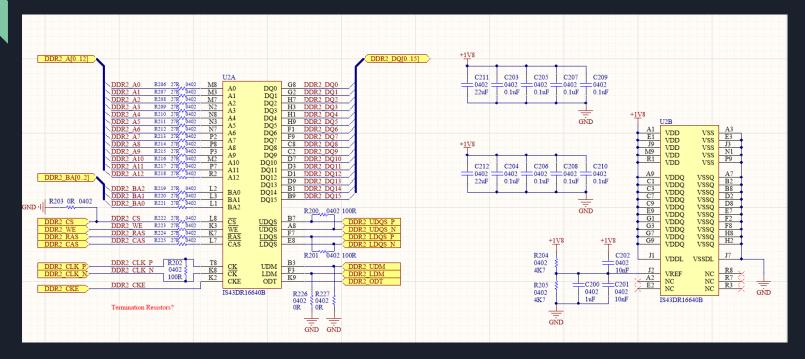
Schematics - DDR2 Memory



Package Pinout

FPGA Bank 34 & 35 IO assignments for the RAM

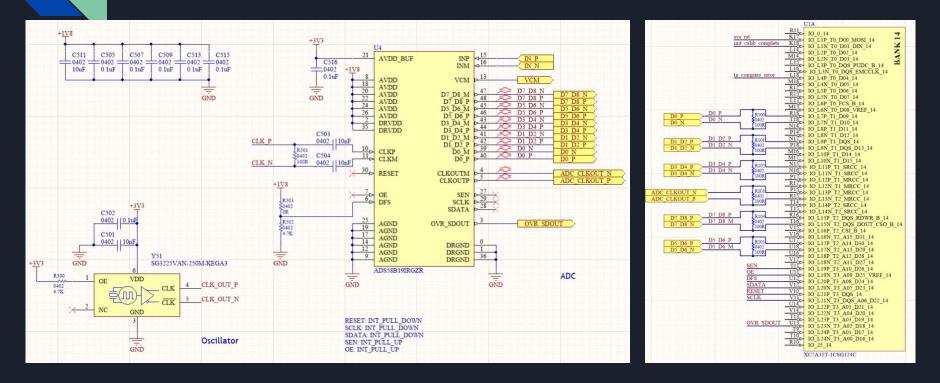




DDR2 Memory & Memory Power Supply

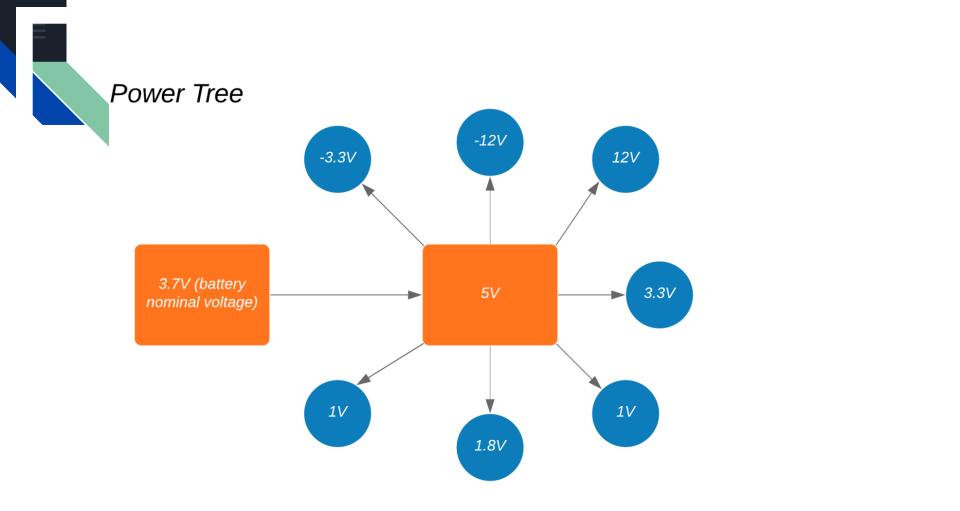


Schematics - ADC



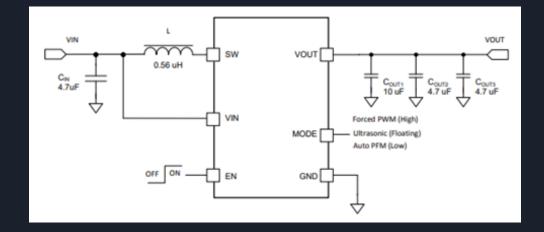
Clock Source & ADC

FPGA Bank 14 IO assignments for the RAM



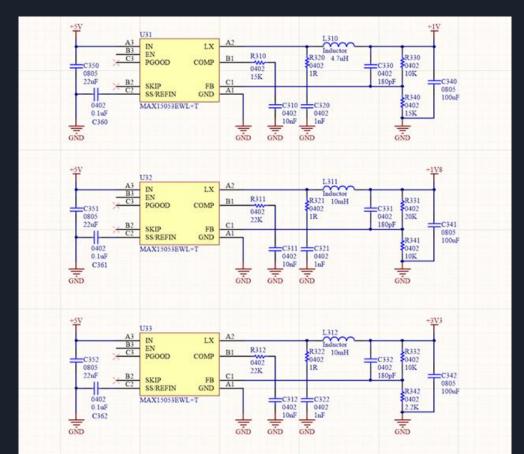


3.7V → 5V Boost Converter



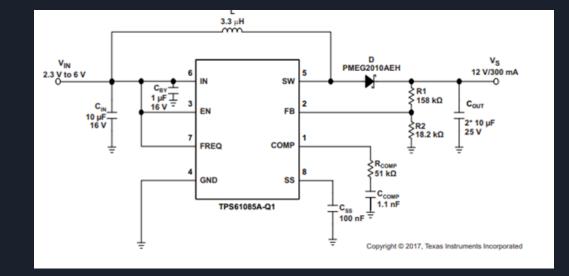


$5V \rightarrow 1V$, 1.8V, 3.3V Buck Converters



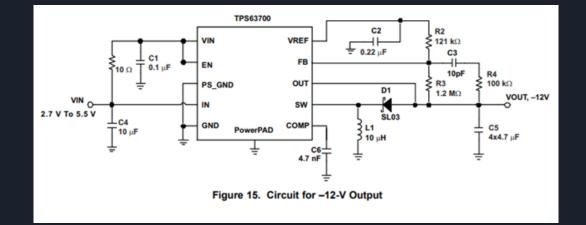


5V → 12V Boost Converter



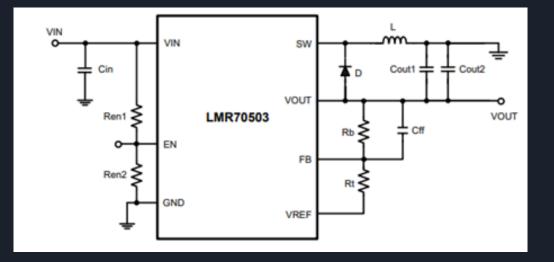


5V → -12V Inverting Converter





5V → -3.3V Buck Boost Inverting Converter





Goals

- Create main test and coding platform which combines all subsystem modules
 - Currently we are designing each subsystem PCB separately and we will combine them into one at the end of this quarter
- Begin testing of overall system
- Begin planning of software architecture



Current Progress

- Reworking AFE design
- Beginning layout work for the FPGA Subsystem
- Beginning main schematic for main system board



Acknowledgements

Thanks to:

- Professor Yoga
- Professor Brewer
- Adi
- Kyle



Any Questions?